

Title (en)

Solution and method for electrochemically depositing a metal on a substrate

Title (de)

Lösung und Verfahren zur elektrochemischen Abscheidung eines Metalls auf ein Substrat

Title (fr)

Solution et procédé pour le dépôt électrochimique d'un métal sur un substrat

Publication

EP 2145986 B1 20100324 (EN)

Application

EP 08075637 A 20080715

Priority

EP 08075637 A 20080715

Abstract (en)

[origin: EP2145986A1] To electroplate a metal layer which has silica particles dispersed therein, a solution and a method for electrochemically depositing a metal on a substrate are provided, wherein the solution contains ions of the metal to be deposited and silica particles, wherein at least one silicon containing organic moiety is provided to said silica particles, said silicon containing organic moiety comprising at least one functional group selected from the group comprising amino, quaternized ammonium, quaternized phosphonium and quaternized arsonium which imparts the silica particles a positive electric charge while being in contact with the solution.

IPC 8 full level

C25D 5/14 (2006.01); **C23F 13/02** (2006.01); **C25D 15/02** (2006.01)

CPC (source: EP KR US)

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Cited by

CN113436775A; PL423721A1; EP3067443A1; US10899932B2; WO2016062880A3

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